

## -20V P-Channel Enhancement Mode MOSFET

### Description

The AP2305AI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -20V$   $I_D = -6.8A$

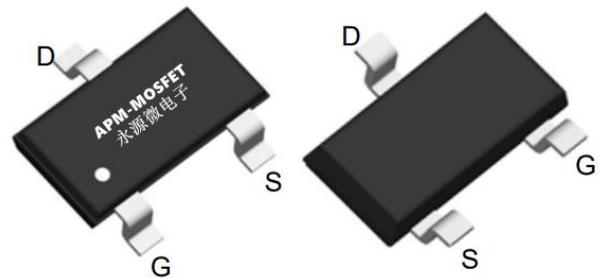
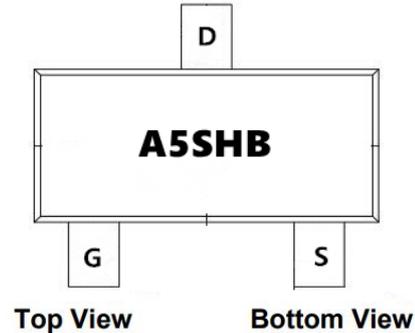
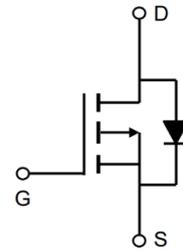
$R_{DS(ON)} < 35m\Omega$  @  $V_{GS} = -4.5V$  (Type: 27m $\Omega$ )

### Application

Battery protection

Load switch

Uninterruptible power supply



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2305AI	SOT23L	A5SHB	3000

### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-6.8	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-5.9	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-22	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	4.31	W
$P_D @ T_A = 70^\circ C$	Total Power Dissipation <sup>3</sup>	0.84	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	125	$^\circ C/W$
$R_{\theta JC}$	Thermal resistance, junction-case	7.4	$^\circ C/W$

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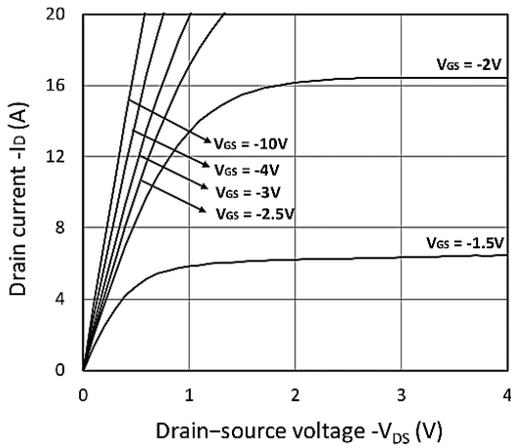
### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	-24	-	V
IGSS	Gate-Body Leakage	$V_{DS}=0V, V_{GS}=\pm 10V$	-	-	$\pm 10$	$\mu A$
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$	-	-	-1	$\mu A$
VGS(th)	Gate-Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.3	-0.65	-1	V
RDS(on)	Drain-Source on-Resistance <sup>3</sup>	$V_{GS}=-4.5V, I_D=-4A$	-	27	35	m $\Omega$
		$V_{GS}=-2.5V, I_D=-4A$	-	36	45	
		$V_{GS}=-1.8V, I_D=-2A$	-	49	60	
Ciss	Input Capacitance	$V_{GS}=0V, V_{DS}=-10V, f=1\text{MHz}$	-	1000	-	pF
Coss	Output Capacitance		-	120	-	
Crss	Reverse Transfer Capacitance		-	100	-	
Qg	Total Gate Charge	$V_{GS}=-4.5V, V_{DS}=-10V, I_D=-4A$	-	12	-	nC
Qgs	Gate-Source Charge		-	1.3	-	
Qgd	Gate-Drain Charge		-	4.5	-	
td(on)	Turn-on Delay Time	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-4A, R_G=3\Omega$	-	12	-	ns
t <sub>r</sub>	Rise Time		-	10	-	
td(off)	Turn-off Delay Time		-	19	-	
t <sub>f</sub>	Fall Time		-	25	-	
VDS	Body Diode voltage <sup>3</sup>	$I_S=-1A, V_{GS}=0V$	-	-	-1	V
IS	Continuous Source Current		-	-	-4	A

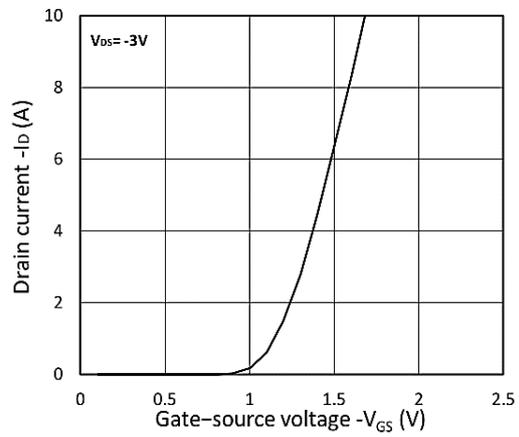
Note :

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width  $\Delta 300\mu s$  , duty cycle  $\Delta 2\%$
- 3、 The power dissipation is limited by 150 $^\circ\text{C}$  junction temperature
- 4、 The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

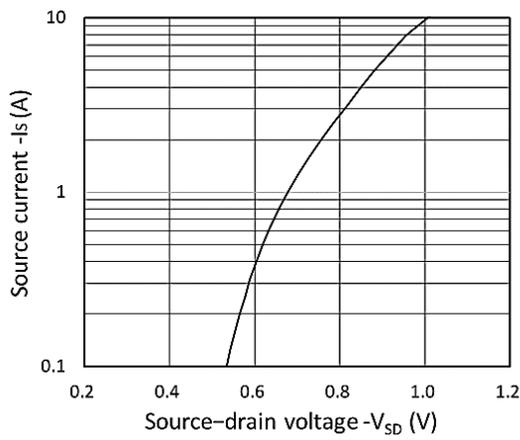
**Typical Characteristics**



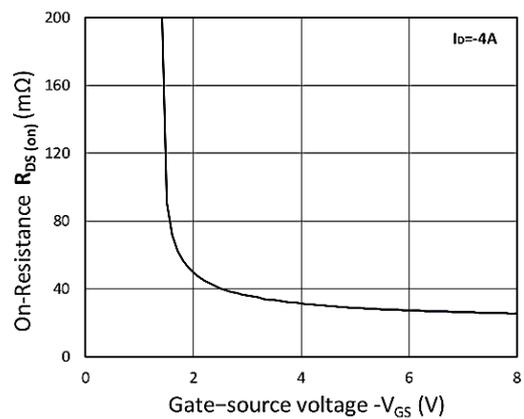
**Figure 1. Output Characteristics**



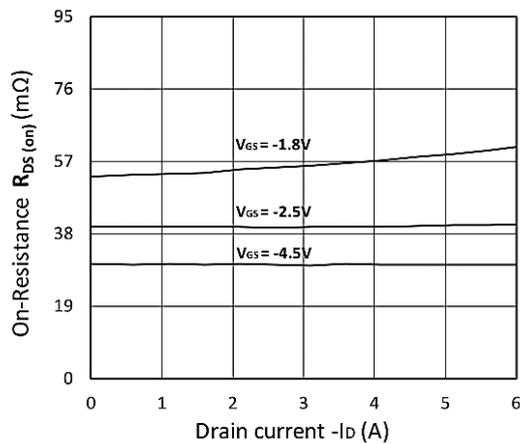
**Figure 2. Transfer Characteristics**



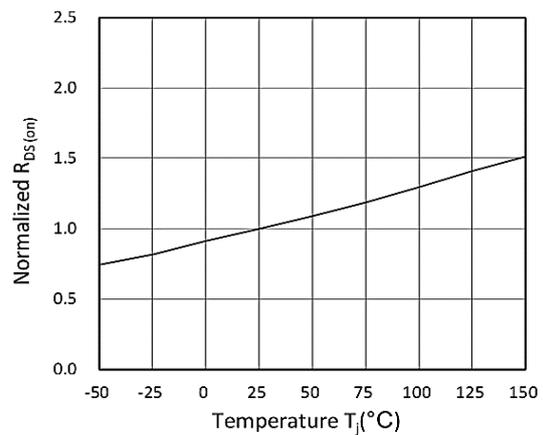
**Figure 3. Forward Characteristics of Reverse**



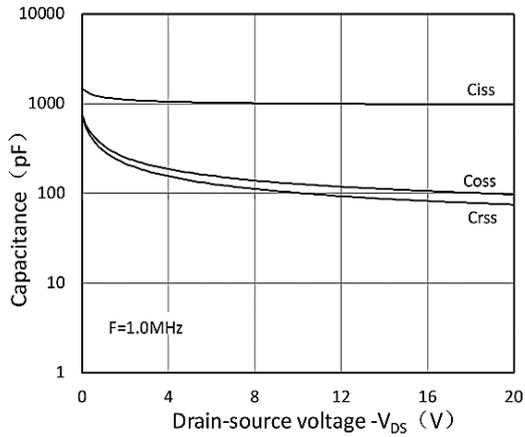
**Figure 4. R<sub>DS(ON)</sub> vs. V<sub>GS</sub>**



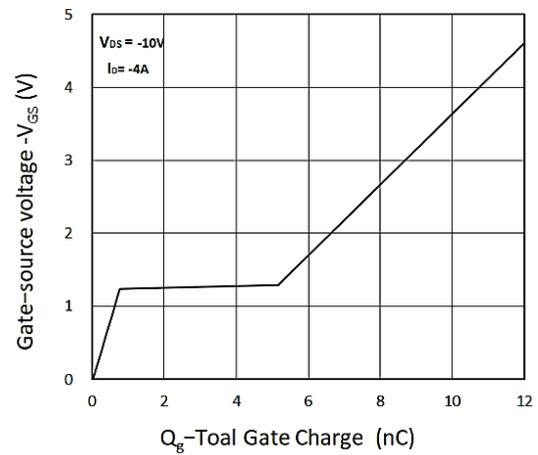
**Figure 5. R<sub>DS(ON)</sub> vs. I<sub>D</sub>**



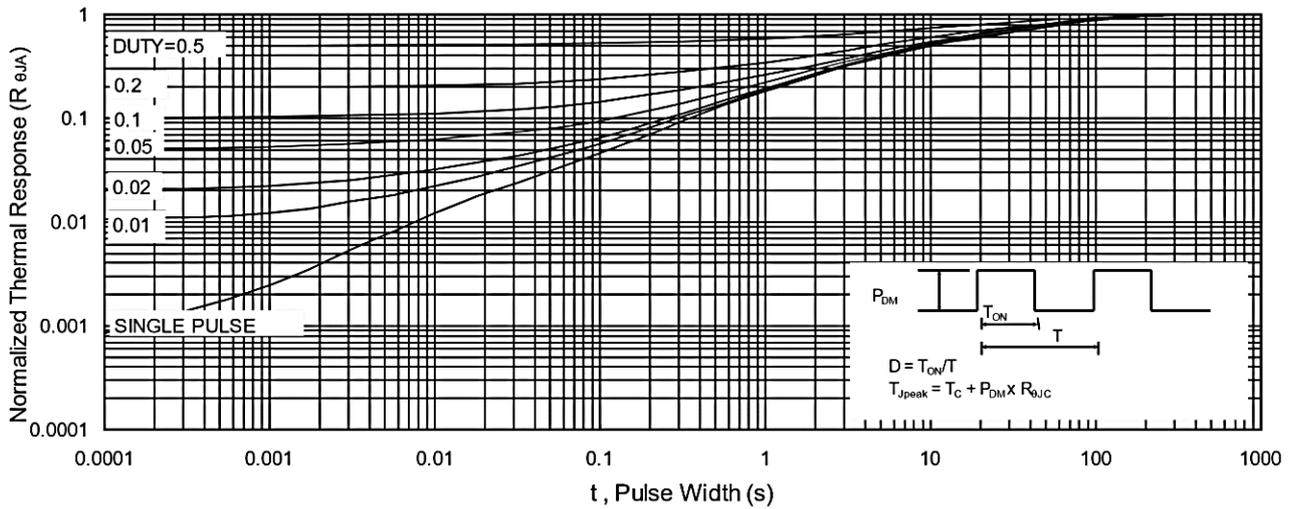
**Figure 6. Normalized R<sub>DS(on)</sub> vs. Temperature**



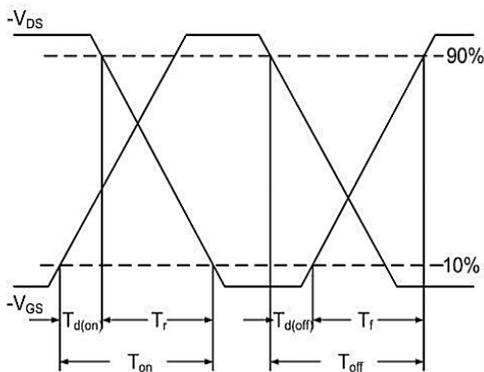
**Figure 7. Capacitance Characteristics**



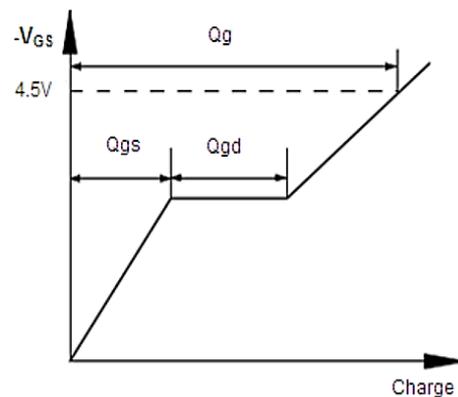
**Figure 8. Gate Charge Characteristics**



**Figure 9 Normalized Maximum Transient Thermal Impedance**

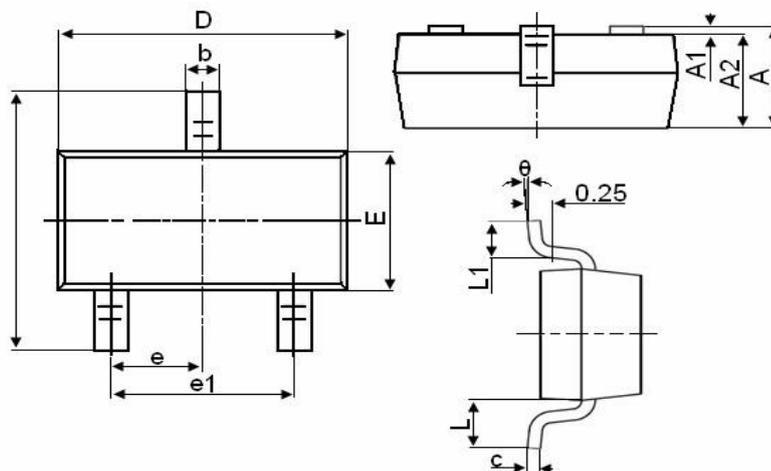


**Figure.10 Switching Time Waveform**



**Figure.11 Gate Charge Waveform**

### Package Mechanical Data-SOT23L-Single



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
$\theta$	0°	8°

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<b>Edition</b>	<b>Date</b>	<b>Change</b>
Rve1.0	2021/4/31	Initial release
Rve1.1	2022/7/12	Reduce RDS

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